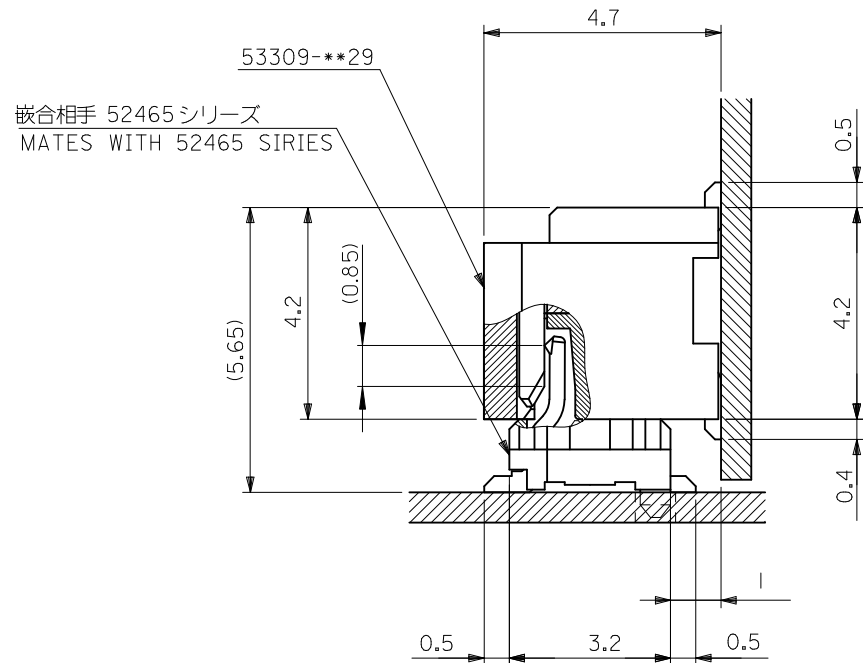


0.4	17.8	16.9	15.2	53309-4029	40	
0.8	17.0	16.1	14.4	-3829	38	
0.4	16.2	15.3	13.6	-3629	36	
0.8	15.4	14.5	12.8	-3429	34	
0.4	14.6	13.7	12.0	-3229	32	
0.8	13.8	12.9	11.2	-3029	30	
0.4	13.0	12.1	10.4	-2829	28	
0.8	12.2	11.3	9.6	-2629	26	
0.4	11.4	10.5	8.8	-2429	24	
0.8	10.6	9.7	8.0	-2229	22	
0.4	9.8	8.9	7.2	-2029	20	
0.8	9.0	8.1	6.4	-1829	18	
0.4	8.2	7.3	5.6	-1629	16	
0.8	7.4	6.5	4.8	-1429	14	
0.4	6.6	5.7	4.0	-1229	12	
53309-**29	0.8	5.8	4.9	3.2	53309-1029	10
MODEL NO.	D	C	B	A	MATERIAL NO.	極数 CKT.

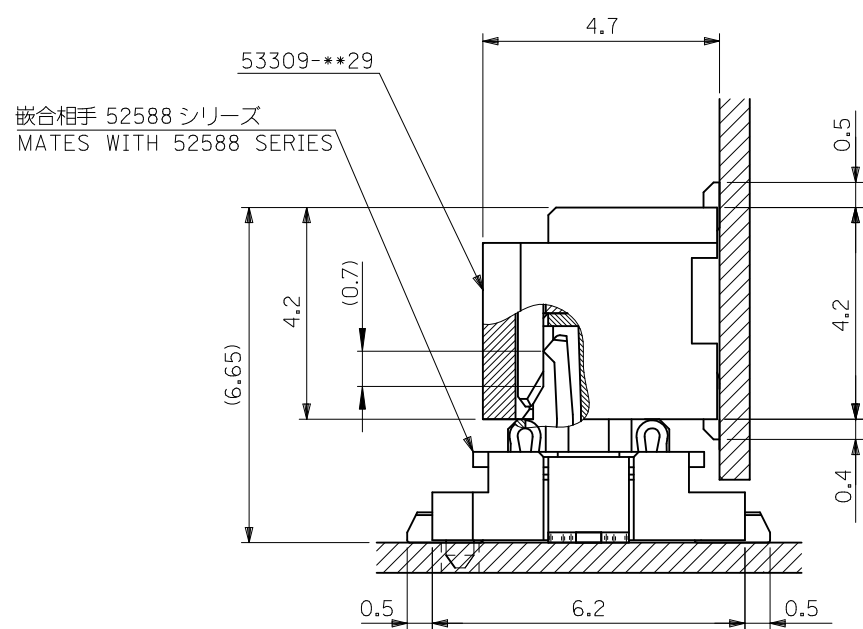
注記 NOTES

1. 嵌合相手: 52465,52588 シリーズ
MATE WITH : 52465,52588 SERIES
2. ウエハーの C から隣接するピンの C 迄の位置を示す。
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.
3. 本製品は 53309-**27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**27

REVISED EC NO: J2010-1285 DRWN: YON002 2009/12/17 CHKD: SMARUYAMA 2009/12/17 APPR: SMARUYAMA 2009/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN. WAFER ASS'Y R/A SMT (WITHOUT BOSS)		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/10	DOCUMENT NO. SD-53309-011		
REV	DESCRIPTION	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SHEET NO. 1 OF 2	



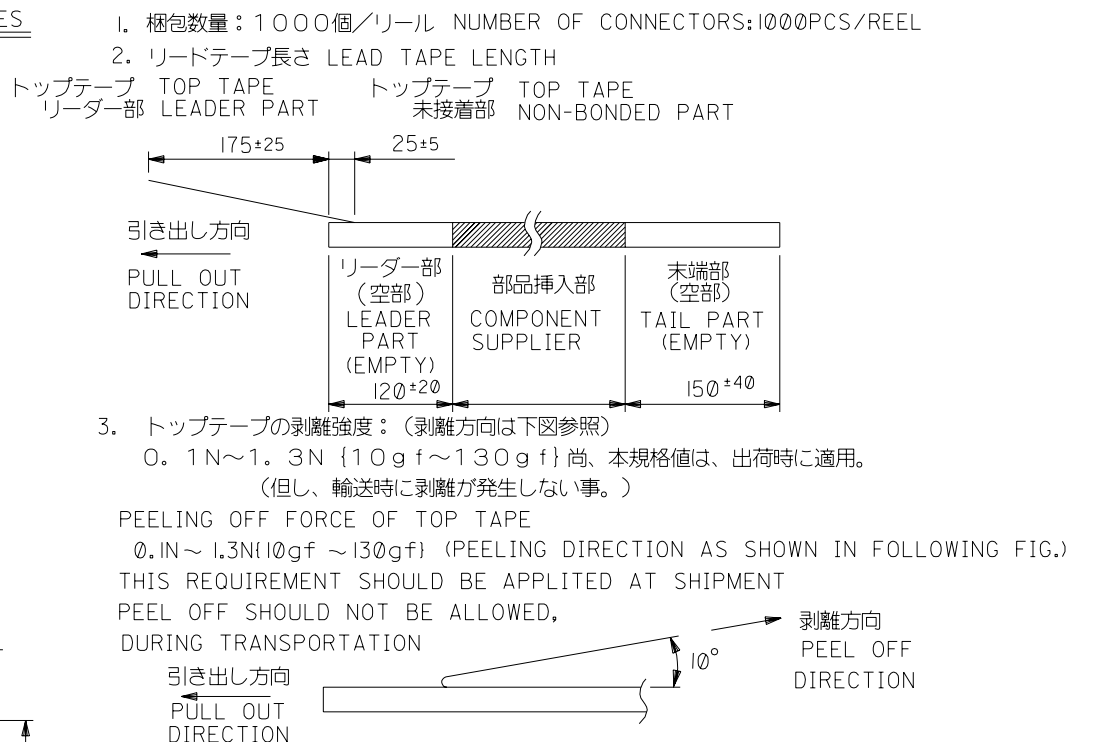
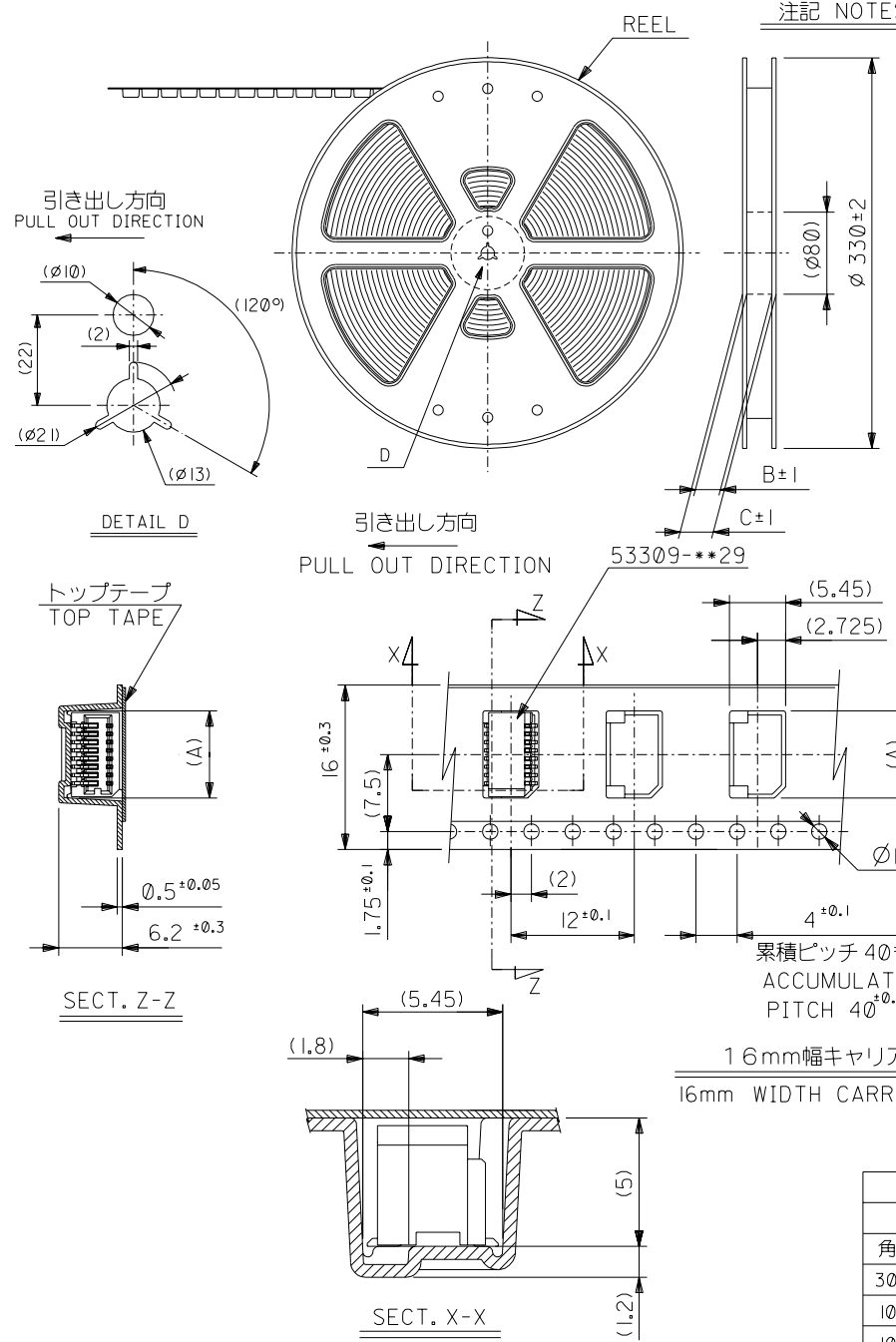
嵌合状態図 (参考)
 MATED DRAWING(REF.)



嵌合状態図 (参考)
 MATED DRAWING(REF.)

REVISED EC NO: J2010-1285 DRWN: YON002 2009/12/17 CHKD: SMARUYAMA 2009/12/17 APPR: SMARUYAMA 2009/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY M. NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN. WAFER ASS'Y R/A SMT(WITHOUT BOSS)	
	10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/03/10	DOCUMENT NO. SD-53309-011	SHEET NO. 2 OF 2
REV	DESCRIPTION	ANGULAR ± 3 °	MATERIAL NO. SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						

DWG. NO.
SD-53309-012



53309-**70				材料 MATERIAL	注記参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
MODEL NO.				仕上げ FINISH	—	
角度 ANGLE	+3°			適用電線範囲 WIRE RANGE	—	TITLE 名称 0.8 BtB Conn Wafer Assy RA SMT Without Boss Embstp Pkg
30以上 OVER	+0.3			被覆外径 INS. RANGE	—	-LEAD FREE-
10以上 OVER 30 UNDER	+0.25			DRAWN BY 04/03/10 M.NINOMIYA	CHK'D BY 04/03/10 K.TOJO	DWG. NO. (SHEET 1 OF 2) REV
未満 10 UNDER	+0.2			記号 LTR	変更内容 REVISION RECORD	SD-53309-012
一般公差 GENERAL TOLERANCES				DR. CHK.	日付 DATE	0

